



Resources

Before you apply, please read the CHIPS Incentives Program Notice of Funding Opportunity (NOFO) for Commercial Fabrication Facilities (<https://nist.gov/chips/notice-funding-opportunity-commercial-fabrication-facilities>). The NOFO provides detailed information about the program objectives and requirements applicants will need to meet to receive funding. It also describes the procedures the Department will use to evaluate and select applications for funding.

Resources (7)

[Grants.gov](#)

[Workforce Development and Child Care Planning Guide](#)

[Notice of Funding Opportunity: CHIPS Incentives Program – Commercial Fabrication](#)

[Informational webinars](#)

[Vision for Success: Commercial Fabrication Facilities](#)

[Frequently Asked Questions](#)

[Sam.gov](#)



User Support

For issues related to the CHIPS Incentives Program portal such as logging in, adding additional users, navigating the website or application intake system, or uploading forms or templates, please contact apply@chips.gov.

For program-related questions, including program guidelines in the Notice of Funding Opportunity (NOFO), the application or application forms and templates, questions on program eligibility including eligible program costs or activities, the application review process, or program technical assistance, please contact the program team at apply@chips.gov.



Welcome, Cary ArchierePortal

My Incentives Request(s)

Incentives Request Number: CHIPS-001315
Name of Application:
Statement Of Interest: Draft
Pre-Application: Not Started
Application: Not Started
Application Pipeline: Front-End and Back-End
Commercial Fabrication Facilities

[View Application](#)

[Start Your Submission](#)

Any communication, data, or other information stored or transmitted on this system may be disclosed or used for any lawful Government purpose. This includes, but is not limited to, statutorily required disclosures to other Executive Branch agencies or offices, Congress, and the U.S. Government Accountability Office pursuant to 15 U.S.C § 4652.

By voluntarily furnishing information through this system, you are indicating your consent for the CHIPS Program Office to use the information you submit for the purposes stated.



Application Workspace Application Team Submissions

Front-End and Back-End Commercial Fabrication Facilities

Under the currently released NOFO, this application pipeline is for leading-edge, current-generation, and mature-node front-end manufacturing, and back-end production facilities.

[Change Application Pipeline](#)

Statement of Interest

OMB Control Number: 0693-0091
Expiration Date: 8/31/2023

[View Burden Statement](#)

Acknowledgement

SECTION STATUS
Not Started

[Get Started](#)

Statement of Interest

SECTION STATUS



Burden Statement

A Federal agency may not conduct or sponsor, and a person is not required to respond to, nor shall a person be subject to a penalty for failure to comply with an information collection subject to the requirements of the Paperwork Reduction Act of 1995 unless the information collection has a currently valid OMB Control Number. The approved OMB Control Number for this information collection is . Without this approval, we could not conduct this information collection. Public reporting for this information collection is estimated to be approximately 30 minutes per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing the information collection. All responses to this information collection are required to obtain benefits. Send comments regarding this burden estimate or any other aspect of this information collection, including suggestions for reducing this burden to the National Institute of Standards and Technology at: askchips@chips.gov.

Change Application Pipeline

OMB Control Number: 0693-0091
Expiration Date: 8/31/2023

View Burden Statement

Acknowledgement

SECTION STATUS
Not Started

Get Started

Statement of Interest

SECTION STATUS
Not Started

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Statement of Interest

OMB Control Number: 0693-0091
Expiration Date: 8/31/2023

Acknowledgement

Any communication, data, or other information stored or transmitted on this system may be accessed and used by federal employees, consultants and contractors in accordance with Section IV.C. of the CHIPS Incentives Program – Commercial Fabrication Facilities Notice of Funding Opportunity (CHIPS-CFF NOFO). By voluntarily furnishing information through this system, the applicant consents to such access and use.

I acknowledge the above statement.

Next

Acknowledgement

Statement of Interest

Submit Statement

Not Started

Pre-Application

OMB Control Number: 0693-0094
Expiration Date: 09/30/2023

View Burden Statement

Applicant Organization Information

Consistent with the Notice of Funding Opportunity (NOFO) for the CHIPS Incentives Program – Commercial Fabrication Facilities, NIST will treat the submitted information as confidential business information (CBI). As a result, NIST will strive to protect the submitted information by applying controls commensurate with the FIPS-199 high for confidentiality level. Information that is populated in structured questions will automatically be labeled as Controlled Unclassified Information – confidential business information (CUI//PROPIN).

Provide the legal name of the entity applying for CHIPS Incentives. Note, this is not the name of the individual submitting the statement of interest.

* Potential Applicant Name

Corporate Parent Name

Have you registered for a SAM.gov account?

* Response Yes No
UEI #

Are there other entities (e.g., customers, suppliers, investors, advisors) you anticipate partnering with in a meaningful way?

* Response

Contact Information

* First Name * Last Name

* Title * Phone

* Email

* Street 1

Street 2

* Country/Area * City * State

* ZIP code

* Organization Website

Save and Next

Steps

- Applicant Organization Information
- Project Information
- Generate PDF
- Confirmation

Project Information

Project(s) Description, i.e. description of the construction, expansion, or modernization activities for each proposed facility at a single location; resulting products that will be manufactured, along with information on the scale, size, and capacity of production, and any known timelines (max. 3000 characters)

* Response

Product End Market Application, i.e., description of the types of customers and which end markets will be served by the technology being produced from each proposed facility (max. 500 characters)

* Response

Site Location

* City * State * ZIP code

Not Determined At This Time

Project Type(s)

* Response

Facility Type(s) (Please select all that apply)

- * Response
- Leading-Edge Facilities
 - Current-Generation Facilities
 - Mature Node Facilities
 - Back-End Production Facilities
 - Semiconductor Materials and Manufacturing Equipment Facilities
 - Research and Development Facilities
 - Wafer Manufacturing
 - Other

If other, please specify

Steps

- Applicant Organization Information
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Back-End Production Facilities
 Semiconductor Materials and Manufacturing Equipment Facilities
 Research and Development Facilities
 Other
 If other, please specify:

Product Information - Leading-Edge Facilities selected
 Technology Segment (Leading-Edge Facilities)
 * Response
 Logic (below 5nm processes)

Expected Total Capital Expenditures for all proposed projects - Please provide the narrowest range possible:
 * Minimum: \$ 1,500,000.00 * Maximum: \$ 2,000,000.00
 Optional commentary on range provided for Expected Total Capital Expenditures (max. 500 characters)
 Response:

Estimated peak monthly unit production capacity (e.g. wafers per month, components per month)
 * Quantity: 1500 Not Applicable
 Please specify unit used
 * Unit: Wafers

CHIPS Application Information
 Do you expect your next submission to be a pre-application or full application? The Department strongly encourages pre-applications for potential applicants for current-generation, mature-node, or back-end production facilities and for potential applicants that are in earlier stages of application development.
 * Response

Optional commentary on range provided for Expected Total Capital Expenditures (max. 500 characters)
 Response:

Estimated peak monthly unit production capacity (e.g. wafers per month, components per month)
 * Quantity: 1500 Not Applicable
 Please specify unit used
 * Unit: Wafers

CHIPS Application Information
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 * Response
 Pre-Application

Expected Timeline for Next Submission (Month) (for submission dates, refer to Executive Summary in the CHIPS-CFF NOFO)
 * Month: March

Expected Timeline for Next Submission (Year) (for submission dates, refer to Executive Summary in the CHIPS-CFF NOFO)
 * Year: 2024

Is there any other information about the potential application that we should know? (max. 1500 characters)

Acknowledgement SECTION STATUS: Not Started

Statement of Interest

OMB Control Number: 0693-0091
Expiration Date: 11/2023

Acknowledged

Statement of Interest

Submit Statement

Pre-Application

OMB Control Number: 0693-0094

Confirmation

You may download a PDF of your Statement of Interest using the link below.

[Download Link](#)

[Finish](#)

Steps

- Applicant Organization Information
- Project Information
- Generate PDF
- Confirmation

Under the currently released NOFO, this application pipeline is for leading-edge, current generation, and mature-node front-end manufacturing...

Change Application Pipeline

Statement of Interest

Acknowledged

Statement of Interest

Submit Statement

Pre-Application

Acknowledged

Coverage

Project

Finance

CHIPS

Environment

Not Started

Attest and Submit

Use of Information

Information submitted in the Statement of Interest (SOI) is being provided to the U.S. Department of Commerce (DOC) for informational and planning purposes. Any information contained in the SOI will not become part of any subsequent application package or be used as part of the award review and selection process; further, the contents of this submission shall not be considered binding and the potential applicant may change any information provided in the SOI as part of any subsequent Pre-Application and Full Application submissions.

DOC recognizes the importance of protecting confidential business information and will follow applicable laws to protect such information, including, for example, the CHIPS Act, the Trade Secrets Act, and the Freedom of Information Act. Please refer to Section IV.C of the CHIPS Incentives Program – Commercial Fabrication Facilities Notice of Funding Opportunity (CHIPS-CFF NOFO) for a further discussion of these laws. By submitting this SOI, the potential applicant represents that it has read Section IV.C of the CHIPS-CFF NOFO information and acknowledges and agrees that the information contained in the SOI may be used by DOC in accordance with that section.

Submission Certifications

<p>Attestation</p> <p>The individual submitting the Statement of Interest certifies on behalf of the applicant entity that the applicant information and data submitted and the representations made in the Statement of Interest are true, complete and accurate, to the best of the applicant's knowledge and belief after due inquiry.</p> <p><input type="checkbox"/></p>
<p>Attestation</p> <p>The individual submitting the Statement of Interest certifies on behalf of the applicant that the applicant understands that CPO and the Department of Commerce will rely on the accuracy and completeness of the applicant information and data submitted and the representations made in the Statement of Interest and that any false, fictitious or fraudulent statement or representation made in the Statement of Interest may be the basis for rejection of the Statement of Interest or subject the applicant to criminal, civil, or administrative penalties. (18 U.S. Code, Section 1001.)</p> <p><input type="checkbox"/></p>
<p>Attestation</p> <p>The individual submitting the Statement of Interest certifies on behalf of the applicant that the applicant understands that any applicant information and data contained in the Statement of Interest may be accessed and used by federal employees, consultants and contractors in accordance with CHIPS-CFF NOFO, Section IV.C. (Confidential Information).</p> <p><input type="checkbox"/></p>
<p>Attestation</p> <p>The individual submitting the Statement of Interest certifies that they possess the full legal power and authority to submit the Statement of Interest and make the preceding certifications on behalf of the applicant.</p> <p><input type="checkbox"/></p>

Steps

- Attest and Submit
- Generate PDF
- Confirmation

Front-End and Back-End Commercial Fabrication Facilities
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Change Application Pipeline

The individual submitting the Statement of Interest certifies that they possess the full legal power and authority to submit the Statement of Interest and make the preceding certifications on behalf of the applicant.

Public Communications

Attestation

The individual submitting the Statement of Interest agrees that neither the applicant entity nor any of its affiliates may issue any press release or otherwise publicly disclose the status of the Statement of Interest or the contents of any communications with CPO or the Department of Commerce without CPO's prior written consent.

Attestation

The individual submitting the Statement of Interest certifies that they possess the full legal power and authority to bind the applicant.

Next

View Burden Statement

Front-End and Back-End Commercial Fabrication Facilities
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Change Application Pipeline

Statement of Interest

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[Change Application Pipeline](#)

[Withdraw Submission](#)

Statement of Interest

OMB Control Number: 0693-0091
Expiration Date: 8/31/2023

[View Burden Statement](#)

Acknowledgement

SECTION STATUS
Submitted

[Submitted](#)

Statement of Interest

SECTION STATUS
Submitted

[Submitted](#)

Submit Statement of Interest

SECTION STATUS
Submitted

[Submitted](#)